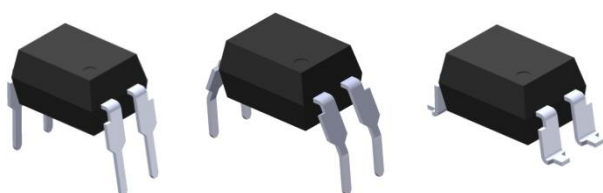
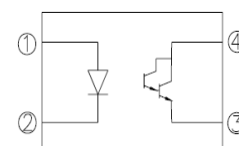


4 PIN DIP PHOTODARLINGTON PHOTOCOUPLER EL815 Series



Schematic



Pin Configuration

1. Anode
2. Cathode
3. Emitter
4. Collector

Features:

- Current transfer ratio (CTR: 600~7500% at $I_F=1\text{mA}$, $V_{CE}=2\text{V}$)
- High isolation voltage between input and output ($V_{iso}=5000\text{Vrms}$)
- Creepage distance $>7.62\text{mm}$
- Operating temperature up to $+110^\circ\text{C}$
- Compact small outline package
- The product itself will remain within RoHS compliant version
- Compliance with EU REACH
- UL approved (No. E214129)
- VDE approved (No. 132249)
- UL and cUL approved (No. E214129)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved
- CQC approved

Description

The EL815 series of devices each consist of an infrared emitting diodes, optically coupled to a photo Darlington detector.

They are packaged in a 4-pin DIP package and available in wide-lead spacing and SMD option.

Applications

- Telephone set, telephone exchangers
- Sequence controllers
- System appliances, measuring instruments
- Signal transmission between circuits of different potentials and impedances

Absolute Maximum Ratings (Ta=25°C)

	Parameter	Symbol	Rating	Unit
Input	Forward current	I_F	60	mA
	Peak forward current (1us, pulse)	I_{FP}	1	A
	Reverse voltage	V_R	6	V
	Power dissipation	P_D	100	mW
	No derating required up to Ta = 100°C			
Output	Power dissipation	P_C	150	mW
	Derating factor (above Ta = 80°C)		5.8	mW/°C
	Collector current	I_C	80	mA
	Collector-Emitter voltage	V_{CEO}	35	V
	Emitter-Collector voltage	V_{ECO}	7	V
Total power dissipation		P_{TOT}	200	mW
Isolation voltage ^{*1}		V_{ISO}	5000	V rms
Operating temperature		T_{OPR}	-55 ~ +110	°C
Storage temperature		T_{STG}	-55 ~ +125	°C
Soldering Temperature ^{*2}		T_{SOL}	260	°C

Notes:

*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1 & 2 are shorted together, and pins 3 & 4 are shorted together.

*2 For 10 seconds

Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

Input

Parameter	Symbol	Min.	Typ.*	Max.	Unit	Condition
Forward Voltage	V_F	-	1.2	1.4	V	$I_F = 20\text{mA}$
Reverse Current	I_R	-	-	10	μA	$V_R = 4\text{V}$
Input capacitance	C_{in}	-	30	250	pF	$V = 0, f = 1\text{kHz}$

Output

Parameter	Symbol	Min.	Typ.*	Max.	Unit	Condition
Collector-Emitter dark current	I_{CEO}	-	-	1	μA	$V_{CE} = 10\text{V}, I_F = 0\text{mA}$
Collector-Emitter breakdown voltage	BV_{CEO}	35	-	-	V	$I_C = 0.1\text{mA}$
Emitter-Collector breakdown voltage	BV_{ECO}	7	-	-	V	$I_E = 0.1\text{mA}$

Transfer Characteristics

Parameter	Symbol	Min.	Typ.*	Max.	Unit	Condition
Current Transfer ratio	CTR	600	-	7500	%	$I_F = 1\text{mA}, V_{CE} = 2\text{V}$
Collector-Emitter saturation voltage	$V_{CE(sat)}$	-	0.8	1.0	V	$I_F = 20\text{mA}, I_C = 5\text{mA}$
Isolation resistance	R_{IO}	5×10^{10}	-	-	Ω	$V_{IO} = 500\text{Vdc}, 40\text{--}60\% \text{ R.H.}$
Floating capacitance	C_{IO}	-	0.6	1.0	pF	$V_{IO} = 0, f = 1\text{MHz}$
Cut-off frequency	f_c	-	6	-	kHz	$V_{CE} = 5\text{V}, I_C = 2\text{mA}, R_L = 100\Omega, -3\text{dB}$
Rise time	t_r	-	60	300	μs	$V_{CE} = 2\text{V}, I_C = 10\text{mA}, R_L = 100\Omega$
Fall time	t_f	-	53	250	μs	

* Typical values at $T_a = 25^\circ\text{C}$

Typical Electro-Optical Characteristics Curves

Figure 1. Forward Current vs Forward Voltage

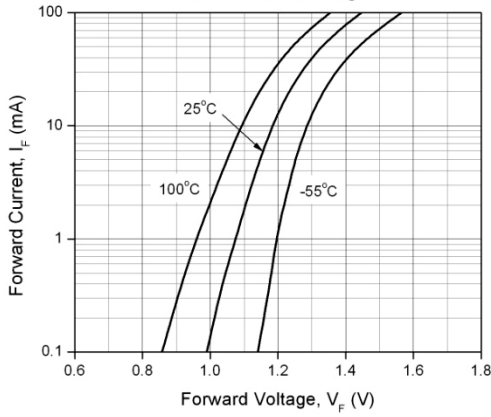


Figure 2. Current Transfer Ratio vs. Ambient Temperature

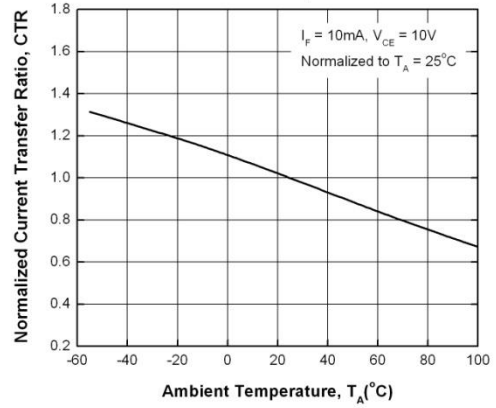


Figure 3. Normalized Current Transfer Ratio vs Forward Current

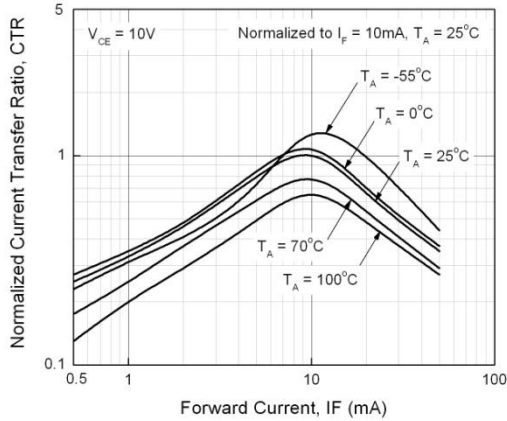


Figure 4. Collector Dark Current vs Ambient Temperature

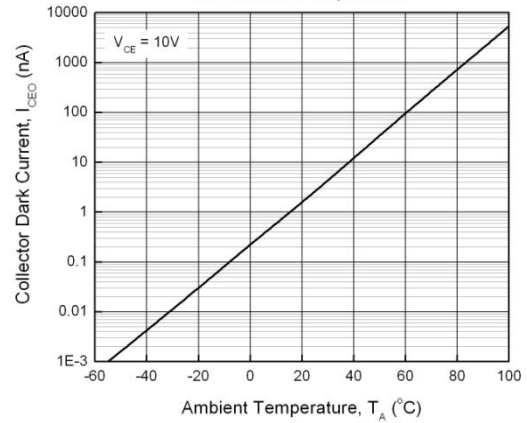


Figure 5. Turn-on Time vs Forward Current

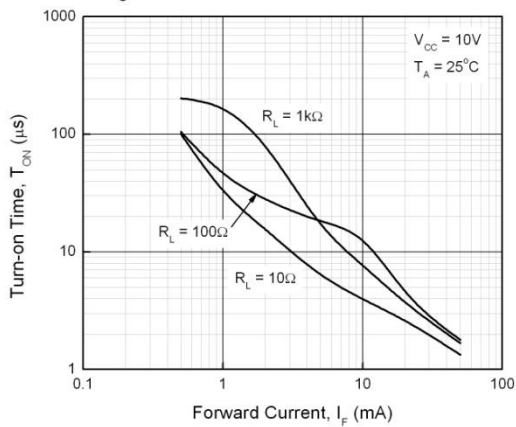
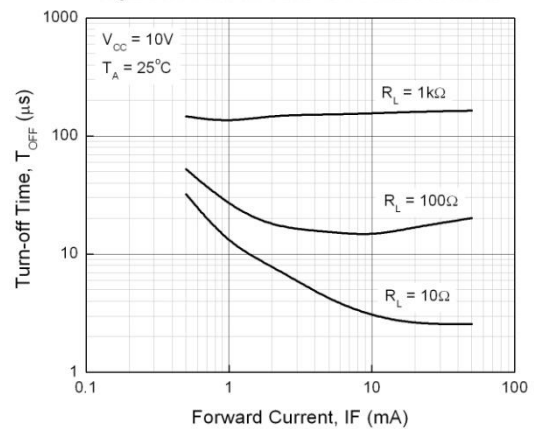


Figure 6. Turn-off Time vs Forward Current



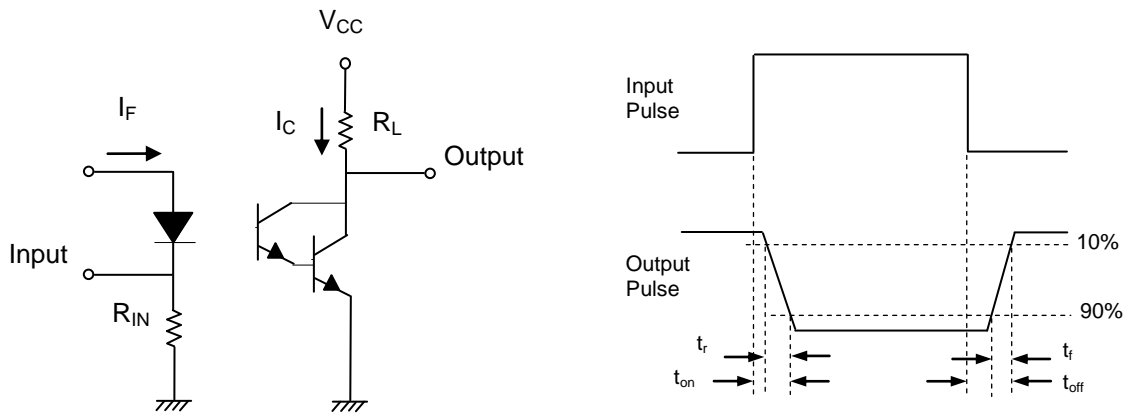


Figure 7. Switching Time Test Circuit & Waveforms

Order Information

Part Number

EL815X(Z)-V

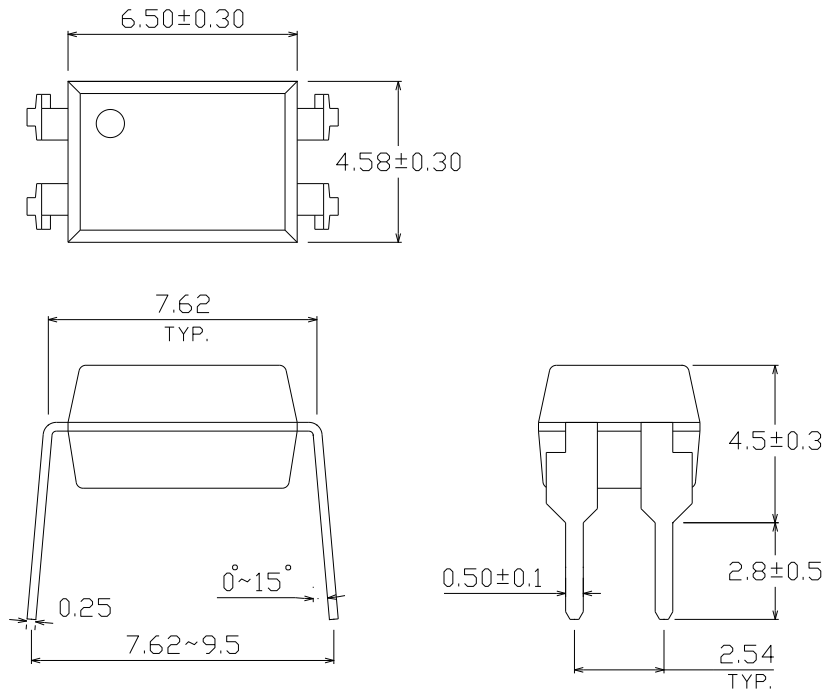
Note

- X = Lead form option (S, S1, M or none)
- Z = Tape and reel option (TA, TB ,TU, TD or none).
- V = VDE safety (optional).

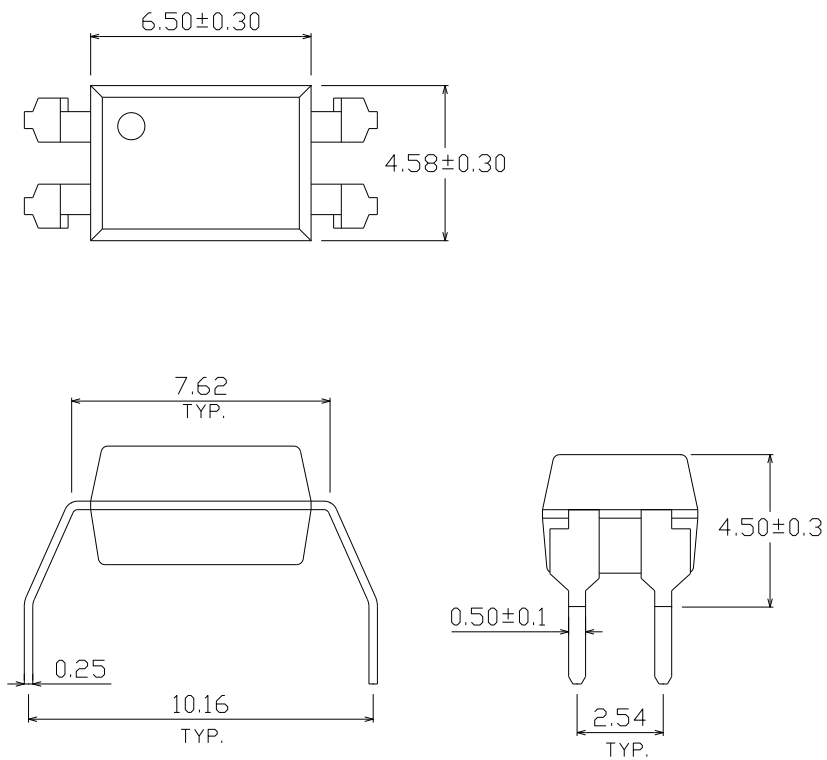
Option	Description	Packing quantity
None	Standard DIP-4	100 units per tube
M	Wide lead bend (0.4 inch spacing)	100 units per tube
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel
S1 (TA)	Surface mount lead form (low profile) + TA tape & reel option	1000 units per reel
S1 (TB)	Surface mount lead form (low profile) + TB tape & reel option	1000 units per reel
S (TU)	Surface mount lead form + TU tape & reel option	1500 units per reel
S (TD)	Surface mount lead form + TD tape & reel option	1500 units per reel
S1 (TU)	Surface mount lead form (low profile) + TU tape & reel option	1500 units per reel
S1 (TD)	Surface mount lead form (low profile) + TD tape & reel option	1500 units per reel

Package Dimension (Dimensions in mm)

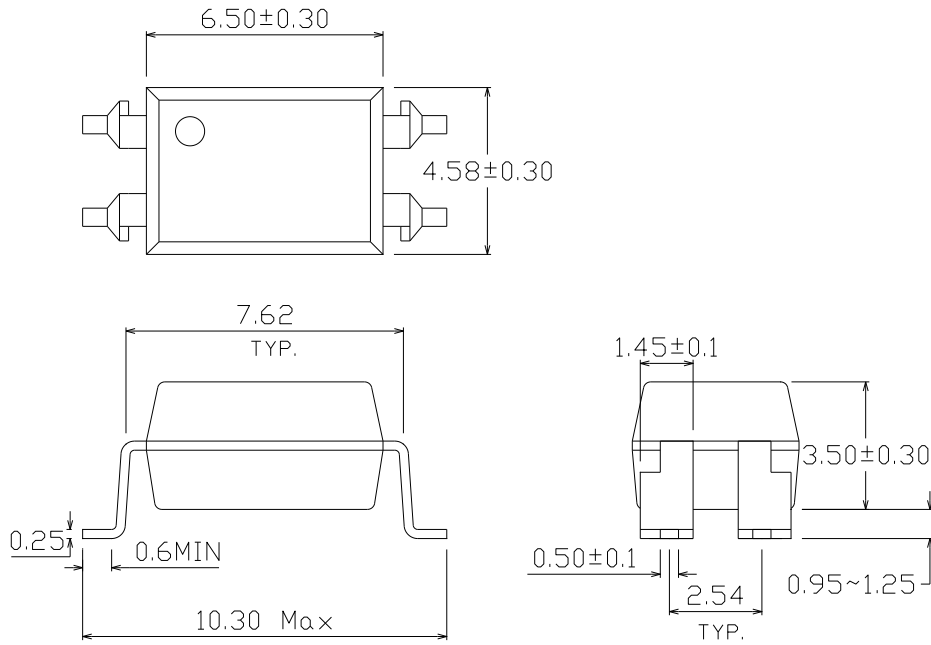
Standard DIP Type



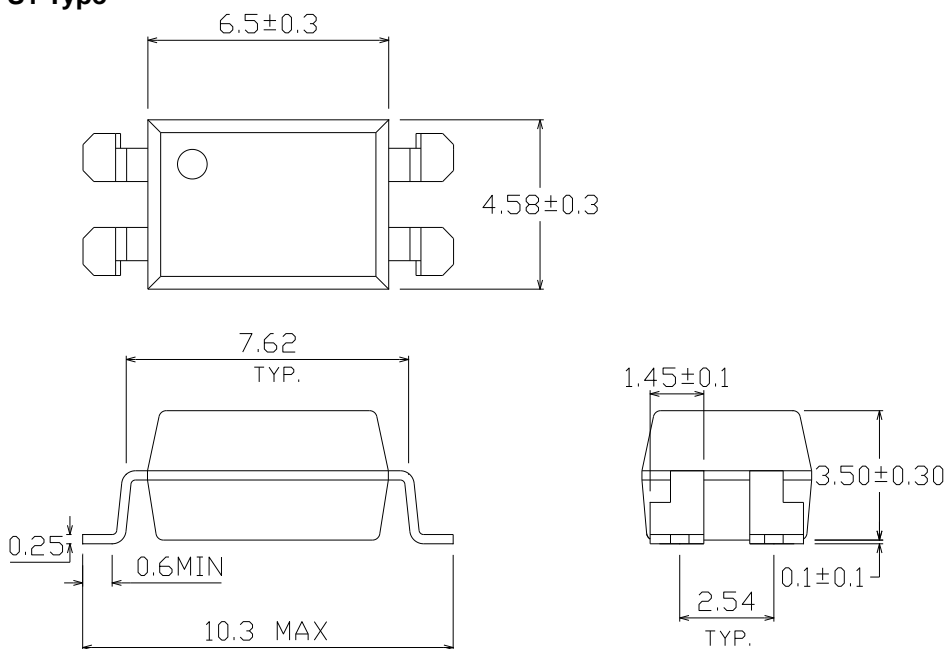
Option M Type



Option S Type

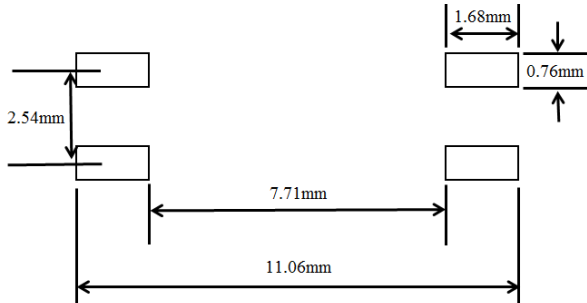


Option S1 Type

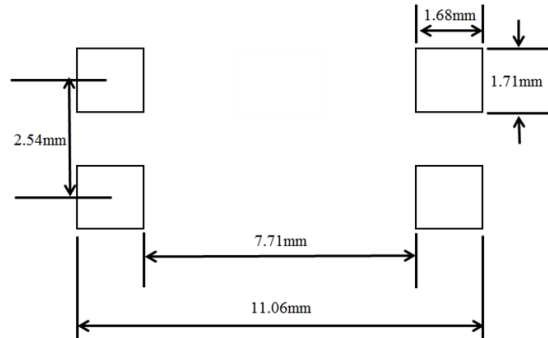


Recommended pad layout for surface mount leadform

For S option



For S1 option



Notes

Suggested pad dimension is just for reference only.
Please modify the pad dimension based on individual need.

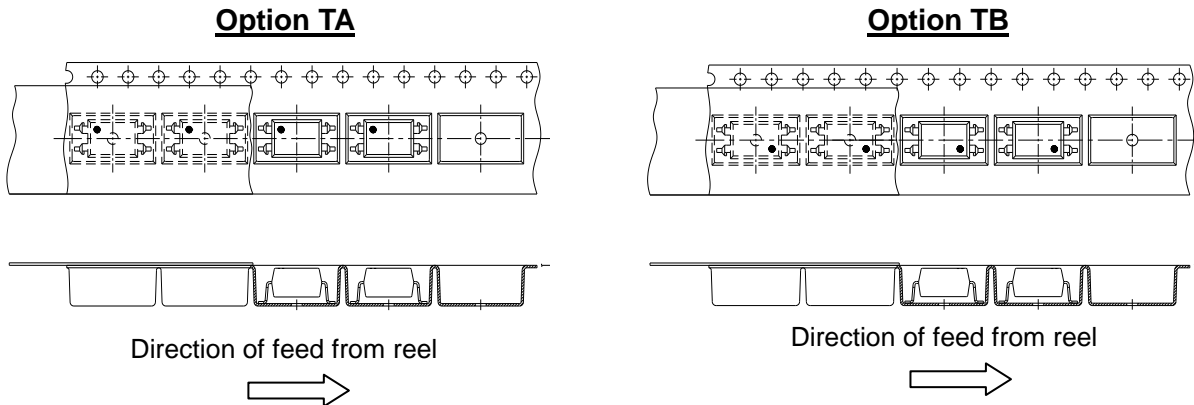
Device Marking



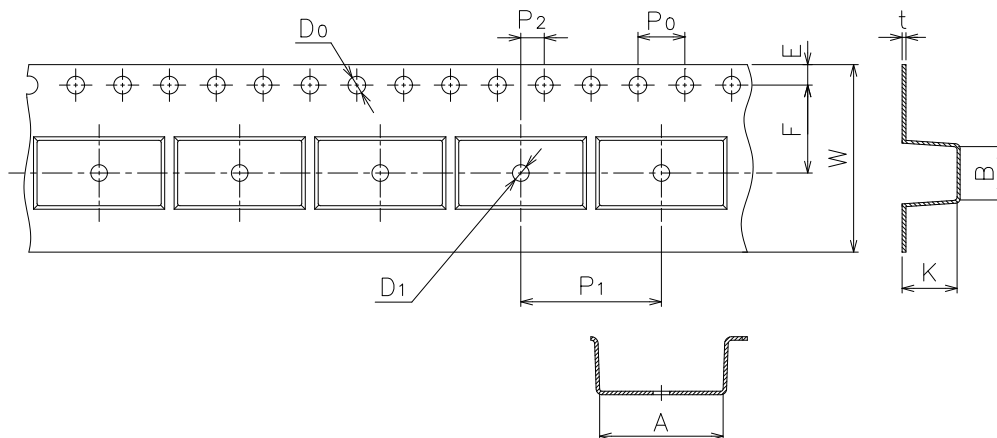
Notes

EL denotes EVERLIGHT
815 denotes Device Number
Y denotes 1 digit Year code
WW denotes 2 digit Week code
V denotes VDE optional

Tape & Reel Packing Specifications



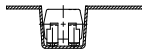
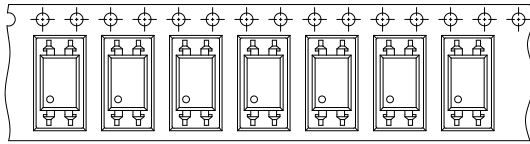
Tape dimensions



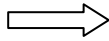
Dimension No.	A	B	Do	D1	E	F
Dimension (mm) S	10.7±0.1	4.65±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.5±0.1
Dimension (mm) S1	10.7±0.1	4.65±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.5±0.1
Dimension No.	Po	P1	P2	t	W	K
Dimension (mm) S	4.0±0.1	12.0±0.1	2.0±0.1	0.4±0.1	16.0±0.3	4.75±0.1
Dimension (mm) S1	4.0±0.1	12.0±0.1	2.0±0.1	0.4±0.1	16.0±0.3	3.90±0.1

Tape & Reel Packing Specifications

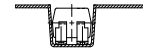
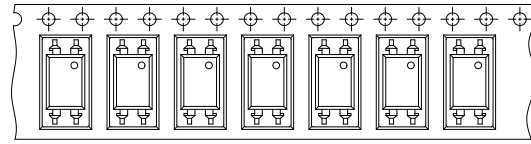
Option TD



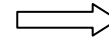
Direction of feed from reel



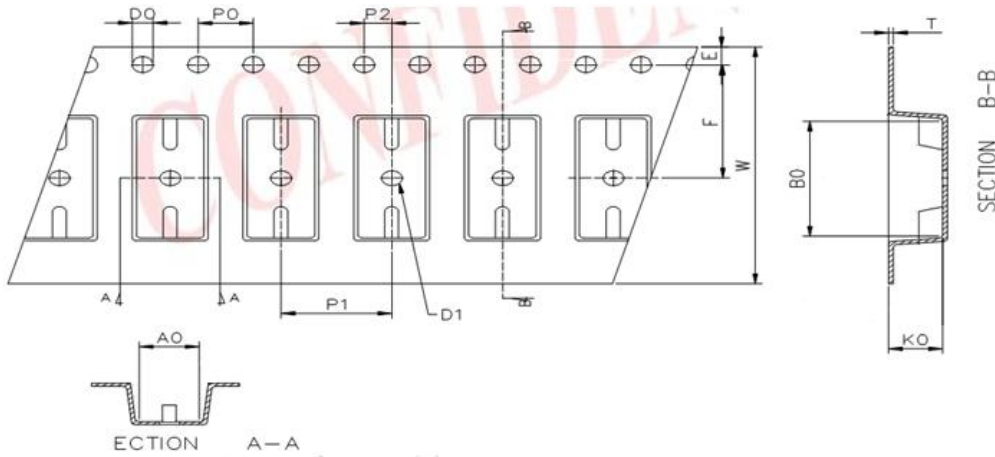
Option TU



Direction of feed from reel



Tape dimensions

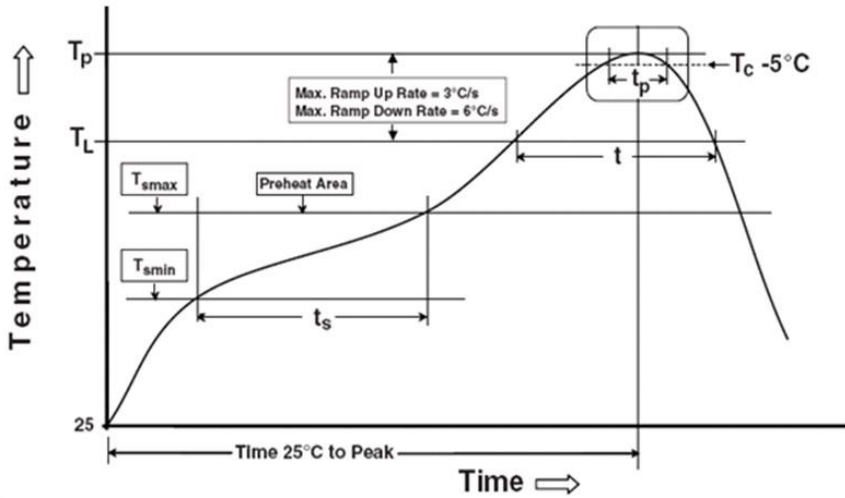


Dimension No.	Ao	Bo	Do	D1	E	F
Dimension (mm)	4.90±0.1	10.40±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.50±0.1
Dimension No.	Po	P1	P2	t	W	Ko
Dimension (mm)	4.00±0.1	8.00±0.	2.00±0.1	0.40±0.1	16.00±0.3	4.60±0.1

Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

Preheat

Temperature min (T_{smin})	150 °C
Temperature max (T_{smax})	200°C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C/second max

Other

Liquidus Temperature (T_L)	217 °C
Time above Liquidus Temperature (t_L)	60-100 sec
Peak Temperature (T_p)	260°C
Time within 5 °C of Actual Peak Temperature: $T_p - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

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2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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